



December 1, 2003

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/655,689 09/05/03 |
| Yian-Liang Kuo et al. |
| AN SBGA DESIGN FOR LOW-K INTEGRATED |
CIRCUITS (IC)

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on December 8, 2003.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

832 12/8/03

U.S. Patent 5,977,633 to Suzuki et al., "Semiconductor Device with Metal Base Substrate Having Hollows," describes a semiconductor device with metal base substrate having hollows.

U.S. Patent 5,223,741 to Bechtel et al., "Package for an Integrated Circuit," describes a package for an integrated circuit structure.

U.S. Patent 5,585,671 to Nagesh et al., "Reliable Low Thermal Resistance Package for High Power Flip Chip IC's," describes a low thermal resistance package for high power flip chip IC's.

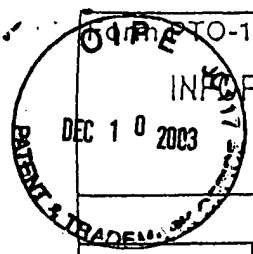
U.S. Patent 6,462,410 to Novotny et al., "Integrated Circuit Component Temperature Gradient Reducer," describes an integrated circuit component temperature gradient reducer.

U.S. Patent 4,748,495 to Kucharek, "High Density Multi-Chip Interconnection and Cooling Package," describes a high density mulitchip interconnection and cooling package.

Sincerely,

A handwritten signature in black ink, appearing to be "SBA", written over the printed name.

Stephen B. Ackerman,
Reg. No. 37761



PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)	DocId Number (Optional) TSMC-03-337	Application Number 10/655,689
	Applicant Yian-Liang Kuo et al.	
	Filing Date 09/05/03	Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	ALING DATE IF APPROPRIATE
	5977633	11/2/99	Suzuki et al.	257	738	5/29/98
	5223741	6/29/93	Bechtel et al.	257	678	9/1/89
	5585671	12/17/96	Nagesh et al.	257	697	10/7/94
	6462410	10/8/02	Novotny et al.	257	707	8/17/00
	4748495	5/31/88	Kucharek	357	82	8/8/85

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.